

AMENDED CLAIMS

1. (Cancelled).
2. (Withdrawn) The process as defined in claim 59, wherein the carrier-connection element combination is arranged in the housing at an angle to a longitudinal direction when said molding compound is poured in.
3. (Withdrawn) The process as defined in claim 59, wherein the carrier-connection element combination is leaned against an inner wall of the housing when molding compound is poured in.
4. (Cancelled).
5. (Previously presented) The process as defined in claim 58, wherein the connection element is rigidly connected to the carrier.
6. (Previously presented) The process as defined in claim 5, wherein a plurality of contact pins of the connection element are connected to the carrier.
7. (Previously presented) The process as defined in claim 5 wherein the connection element is soldered to the carrier.
8. (Previously presented) The process as defined in claim 58, wherein a cup-shaped insert is provided for closing the housing at the front end, said insert being pushed into the housing in the direction of the rear end from the front end.
9. (Previously presented) The process as defined in claim 8, wherein the insert is held on the housing in a force-locking manner after insertion of the insert into the housing.

10. (Previously presented) The process as defined in claim 58, wherein the carrier-connection element combination is placed onto a closure element forming the closed front end.

11. (Previously presented) The process as defined in claim 58, wherein a longitudinal direction of the housing is oriented essentially parallel to a direction of earth's gravitational force during the introduction of at least one of the carrier-connection element combination and the molding compound.

12. (Previously presented) The process as defined in claim 58, comprising controlling the amount of molding compound introduced into the housing.

13. (Previously presented) The process as defined in claim 58, wherein during the capping of the open rear end of the housing, the carrier-connection element combination is aligned in a longitudinal direction of the housing.

14. (Previously presented) The process as defined in claim 58, wherein during the capping of the open rear end of the housing, the carrier-connection element combination is aligned essentially collinear to a longitudinal axis of the housing.

15. (Previously presented) The process as defined in claim 58, wherein the cap is pushed into the housing.

16. (Previously presented) The process as defined in claim 15, wherein the cap is pushed into the housing as far as a stop provided on the cap.

17. (Previously presented) The process as defined in claim 15, wherein the cap is pushed into the housing prior to hardening of

the molding compound.

18. (Previously presented) The process as defined in claim 58, wherein the cap is positioned on the carrier-connection element combination before the carrier-connection element combination is introduced into the housing interior.

19. (Previously presented) The process as defined in claim 18, wherein the carrier-connection element combination is pushed into the housing with the cap positioned thereon.

20. (Previously presented) The process as defined in claim 58, wherein the cap and the connection element are provided with complementary fixing means.

21. (Previously presented) The process as defined in claim 20, wherein during a connection of the cap with the housing, the cap and the carrier-connection element combination are oriented relative to one another such that the respective fixing means can engage on one another.

22-57 (Cancelled).

58. (Previously presented) A process for fabricating a position sensor, comprising:

    providing a housing with a closed front end and an open rear end;

    providing a carrier having an electronic circuit thereon;

    providing an electrical connection element on said carrier to form a carrier-connection element combination to enable an external connection to said electronic circuit;

    introducing said carrier into the open rear end of said housing;

    pouring a molding compound into said open rear end of said

housing for encapsulating said electronic circuit within the housing; and

capping the open rear end of said housing with a cap;

wherein connection portions of said electrical connection element are guided through said cap.

59. (Withdrawn) The process as defined in claim 58, wherein said carrier is introduced into the open rear end of said housing, and said molding compound is then poured around said carrier.

60. (Cancelled).

61. (Previously presented) The process as defined in claim 58, wherein said molding compound is introduced into said housing, and the carrier is then inserted into said molding compound from the open rear end of the housing.

62. (Previously presented) The process as defined in claim 61, wherein said molding compound is poured into said housing from said open rear end.